



Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	Not specified	1	0
F.Mask	Top Solder Mask	Not specified	0.3937008 mils	Not specified	3.3	0
F.Cu	copper		1.377953 mils		1	0
Dielectric	prepreg	FR4	4.330709 mils		4.5	0.02
In1.Cu	copper		1.377953 mils		1	0
Dielectric	core	FR4	47.24409 mils		4.5	0.02
In2.Cu	copper		1.377953 mils		1	0
Dielectric	prepreg	FR4	4.330709 mils		4.5	0.02
B.Cu	copper		1.377953 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937008 mils	Not specified	3.3	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	Not specified	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	62.20 mils
Board overall dimensions:	2000.00 mils x 1500.00 mils		
Min track/spacing:	7.87 mils / 0.00 mils	Min hole diameter:	11.81 mils
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

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Title: ESP-12F APA102 LED Lava Lamp

Size: A4	Date: 2022-12-13	Rev: 1
KiCad E.D.A. kicad (6.0.4)		Id: 1/1